

Title (en)

CARRIER FOIL FOR ELECTRONIC COMPONENTS, FOR LAMINATING INSIDE CHIP CARDS

Title (de)

TRÄGERFOLIE FÜR ELEKTRONISCHE BAUELEMENTE ZUR EINLAMINIERUNG IN CHIPKARTEN

Title (fr)

PELLICULE SUPPORT DESTINEE A DES COMPOSANTS ELECTRONIQUES POUR LAMINAGE DANS DES CARTES A PUCE

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Application

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Abstract (en)

[origin: WO02084585A1] The invention relates to a carrier foil for electronic components, for laminating inside chip cards comprising at least one strip conductor (2) arranged on a carrier foil body and provided with connection regions (3, 4, 5, 6) consisting of a conductive material and used to connect to other electronic components or connecting bridges. Said connection regions (3, 4, 5, 6) comprise a plurality of interconnected partial surfaces (7) consisting of said conductive material, and free surfaces (8) which are arranged between said partial surfaces and which are not coated with said conductive material. The inventive embodiment enables deformation resulting from the difference between the expansion capacity of the carrier foil material and that of the connection region material to be reduced, and simultaneously the adhesion forces between a plastic cover and the actual carrier foil material to be increased in the connection regions. The invention also relates to a chip card comprising the inventive carrier foil and a method for producing said carrier foil.

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